

08-24-2006

EET

TI 60499

To the Director of the U.S. Patent and Trademark

103296030

the new address(es) below

1. Name of conveying party(ies)

1. Masazumi Amagal
2. Kenji Masumoto
- 3.
- 4.

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No**3. Nature of conveyance/Execution Date(s)**

Execution Date(s)

8/9/2006;8/16/2006

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424 Confirmatory License
☐ Other _____

2. Name and address of receiving party(ies)(1) Name Texas Instruments Inc.Street Address: P.O. Box 655474; MS 3999City: Dallas State: TXCountry: USA Zip: 75265

(2) Name _____

Street Address: _____

City: _____ State: _____

Country: _____ Zip: _____

Additional name(s) and Address(es) attached? ☐ Yes ☒ No**4. Application or patent number(s):**

A. Patent Application No.(s)

11 / 466 , 219

☐ This document is being filed together with a new application.

B. Patent No.(s) _____

Additional numbers attached? ☐ Yes ☒ No**5. Name and address to whom correspondence concerning document should be mailed:**Name: Sam Tung

Internal Address: _____

Company: Texas Instruments Inc.Address: P.O. Box 655474; MS 3999City: DallasState TX Zip: 75265Phone Number (972) 917-5355Fax Number (972) 917-4418Email Address y-tung2@ti.com**6. Total number of applications and patents involved:**

1

7. Total Fee (37 CFR 1.21(h) & 3.41) \$40.00

- ☐ Authorized to be charged by credit card
☒ Authorized to be charged to deposit account
☐ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers _____

Expiration Date: _____

b. Deposit Account Number: 20-0668Authorized User Name: Sam Tung**9. Signature**

Signature

8/22/2006

Date

Charles W. Gaines

Name of Person Signing

Total number of Pages including
Cover sheet, attachments and

3

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:
Mail stop Assignment Recordation Services, Director of the USPTO, P.O. Box 1450, Alexandria, V.A. 22313-1450

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ASSIGNMENT

WHEREAS, TEXAS INSTRUMENTS JAPAN, LTD. (hereinafter **TJ**), a Japanese company having its headquarters at 24-1 Nishi-Shinjuku 6-chome, Shinjuku-ku, Tokyo, Japan, under the laws of Japan made application, in its own name, for Letters Patent in Japan in respect of an invention as set forth below;

WHEREAS, the or each below named inventor (hereinafter **INVENTOR**) is the or an inventor of the said invention;

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, having a place of business at 7839 Churchill Way, Mail Station 3999, Dallas, Texas 75251, USA, is desirous of acquiring the entire right, title and interest in and to the said invention outside of Japan, and in and to the U.S. patent application as identified hereinafter and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, by this Assignment, **TJ** and **INVENTOR** sell and assign to the said **TEXAS INSTRUMENTS INCORPORATED**, its successors and assigns the entire right, title and interest in and to the said invention in the U.S.A. and all other countries outside Japan; in and to the U.S. patent application as identified below and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and the right to file applications and obtain patents in its own name in any said other country or group of countries, and to claim priority under the terms of the International Convention for the Protection of Industrial Property or any other relevant convention;

TJ and **INVENTOR** hereby authorize and request the Commissioner of Patents to issue U.S. patents for said invention, or U.S. patents resulting therefrom, insofar as the interest of **TJ** and **INVENTOR** is concerned to the said **TEXAS INSTRUMENTS INCORPORATED**, as assignee of the entire right, title and interest.

TJ and **INVENTOR** further agree to communicate to **TEXAS INSTRUMENTS INCORPORATED** or to its successors, assigns and legal representatives, any facts known to **TJ** and **INVENTOR** respecting the said invention, and at the expense of **TEXAS INSTRUMENTS INCORPORATED**, sign any and all patent applications, assignments, affidavits and other lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, testify in any legal or quasi-legal proceedings and generally do everything possible to aid said **TEXAS INSTRUMENTS INCORPORATED**, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries outside of Japan.

Assignment
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SEMICONDUCTIVE DEVICE HAVING IMPROVED COPPER DENSITY FOR PACKAGE-ON-PACKAGE APPLICATIONS

Title of Invention

Japanese Serial No.:

Filed:

U.S. Application Serial No.:

Filed:

IN WITNESS WHEREOF, this Agreement has been executed as set forth below;

Signed at Tokyo, Japan on August 21, 2006

by Texas Instruments Japan, Ltd.

Name

T. Yamada
Toshiyuki Yamada

Title Representative Director and President

Date

Aug. 21, 2006

and by the INVENTOR:

(1)

Masazumi Amagai
Masazumi Amagai

Ninomiya 17, Tsukuba, Ibaraki 305-0051, Japan
Address

Aug 9, 2006
Date

(2)

K. Masumoto
Kenji Masumoto

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Address

August 16, 2006
Date